Thermal shock response of fine and ultra fine grained tungsten based materials

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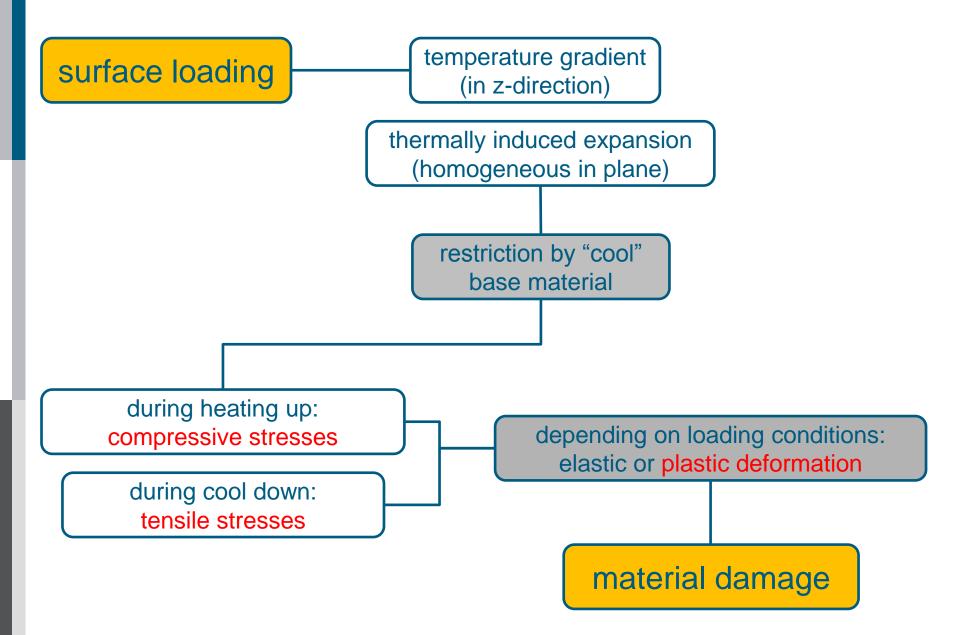
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Introduction – thermal shock response

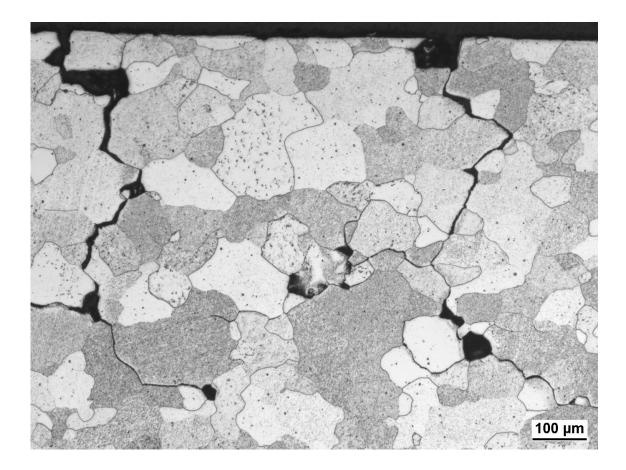






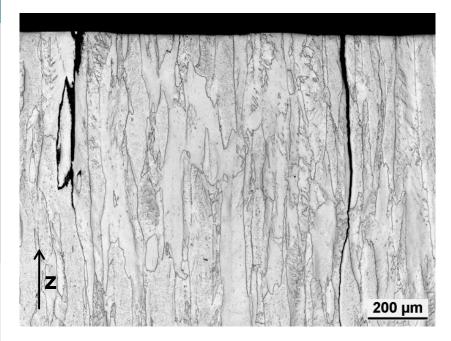
Main problem of tungsten

BRITTLENESS (of grain boundaries)



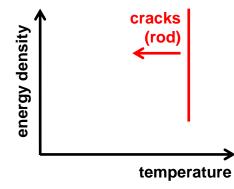


Industrially available grades - ANISOTROPY



ROD

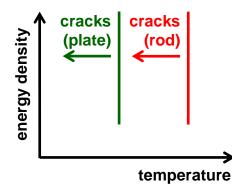
- good mechanical properties in zdirection
- weak mechanical properties in the surface plane
- ⇒ brittle crack formation up to higher temperatures



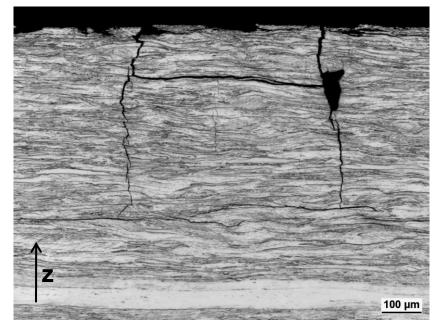


Industrially available grades - ANISOTROPY

- weak mechanical properties in zdirection
- good mechanical properties in the surface plane
- ⇒ brittle crack formation limited to lower temperatures **BUT** crack formation parallel to the surface

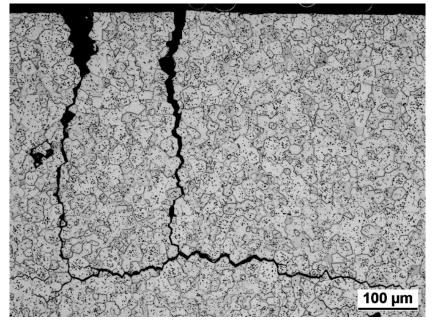


PLATE





ISOTROPIC material, e.g. PIM-W



J. Opschoor et al., Poster P29, PFMC-12, Jülich

- good mechanical properties in all directions
- ⇒ brittle crack formation limited to lower temperatures **BUT** crack formation parallel to the surface

crack formation parallel to the surface determined by

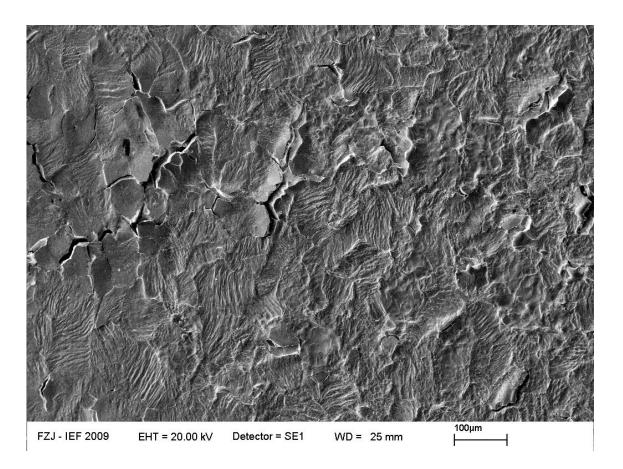
- temperature gradient (pulse duration, power density)
- resulting thermal stresses

recrystallization / grain growth \Rightarrow isotropy BUT: weakening of grain boundaries & reduction of mechanical strength



Additional problem of tungsten

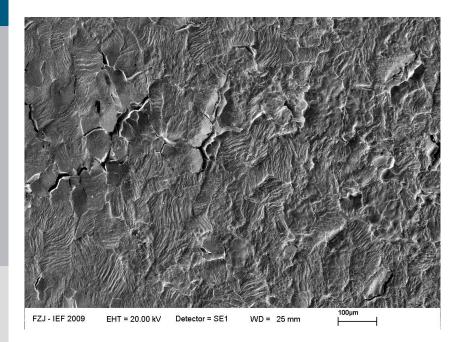
THERMAL FATIGUE





Additional problem of tungsten

THERMAL FATIGUE



depending on

- strength and ductility
- base temperature
- grain size
- ⇒ plastic deformation leads (sooner or later) to crack formation (see poster P69A, Th. Loewenhoff et al.)

Conclusion



A material with good thermal shock resistance needs

- high strength in all directions
 ⇒ isotropy
- high strength of grain boundaries
 alloying, particle reinforcement
- high recrystallization resistance
 alloying, particle reinforcement, low degree of deformation
- high thermal fatigue resistance
 fine grained materials

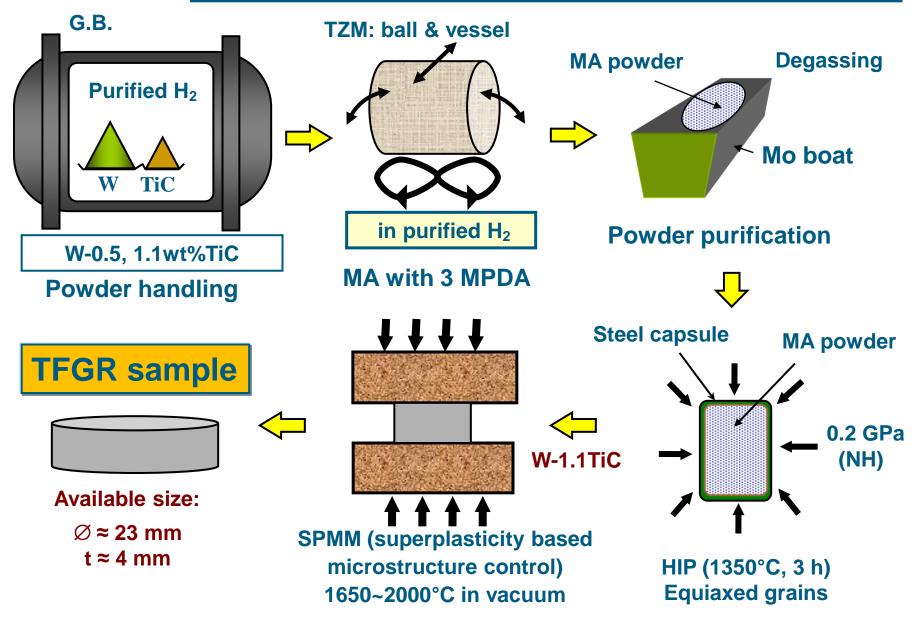
Other needs





Processing

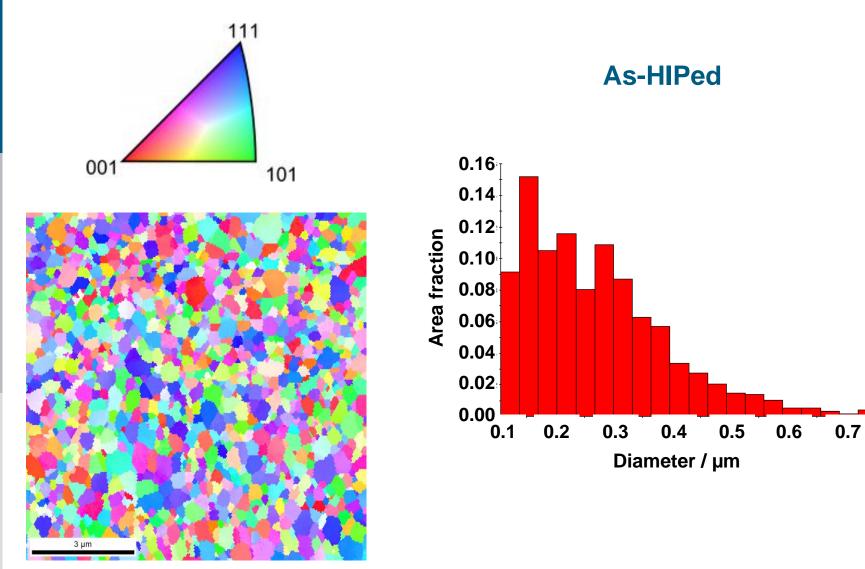




TFGR = Toughness Enhanced Fine Grained Material in the Recrystallized State

Grain distribution in UFG W-0.5TiC

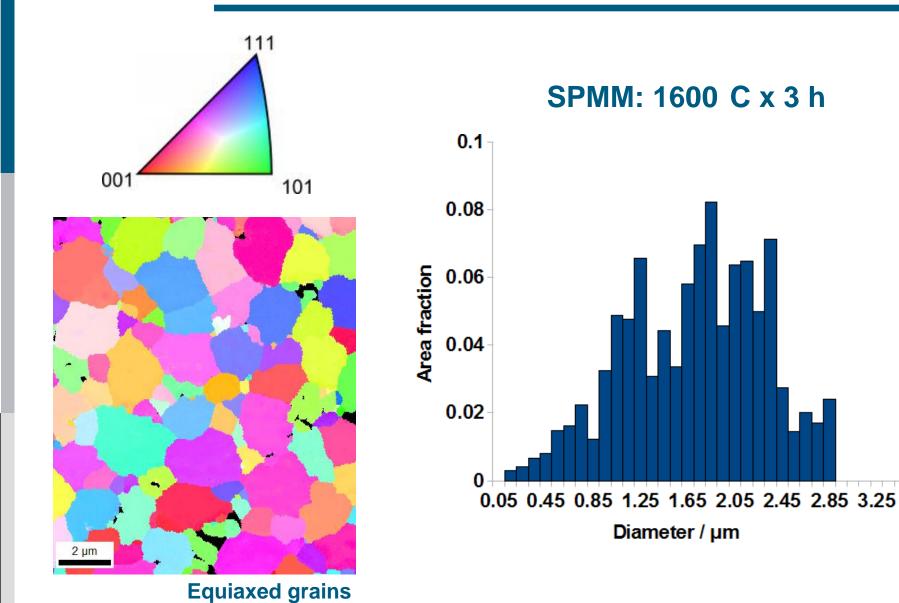




Equiaxed grains

Grain distribution in TFGR W-1.1TiC



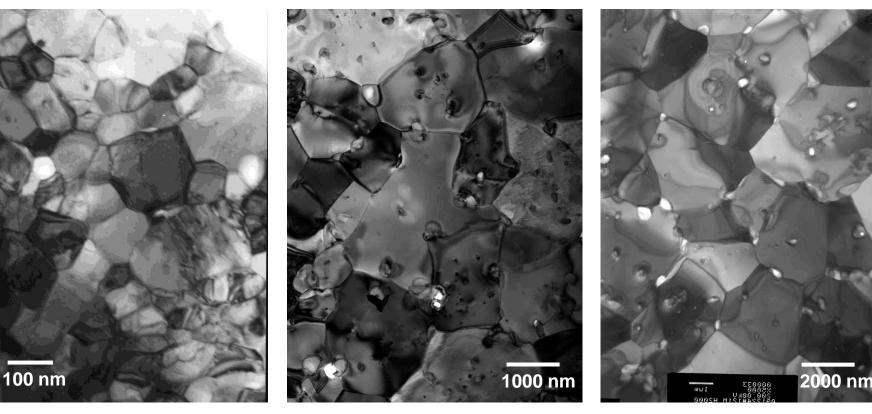


By S. Tsurekawa et al.

Effect of SPMM temp. on microstructure



UFG W-1.1TiC



As-HIPed: 1350 C x 3h

Grain size: 90 nm

SPMM: 1650 C x 3h

Grain size: 1480 nm

SPMM: 1650-2000 C x 3h

Grain size: 2900 nm

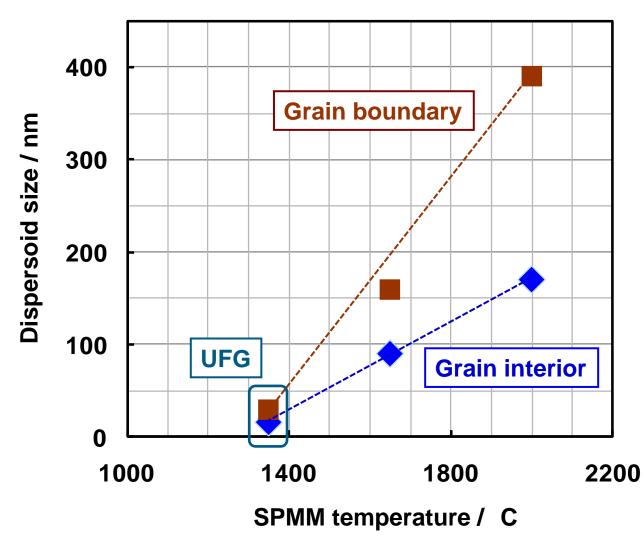
By T. Sakamoto et al.

TFGR W-1.1TiC

Effect of SPMM temp. on TiC dispersoid size



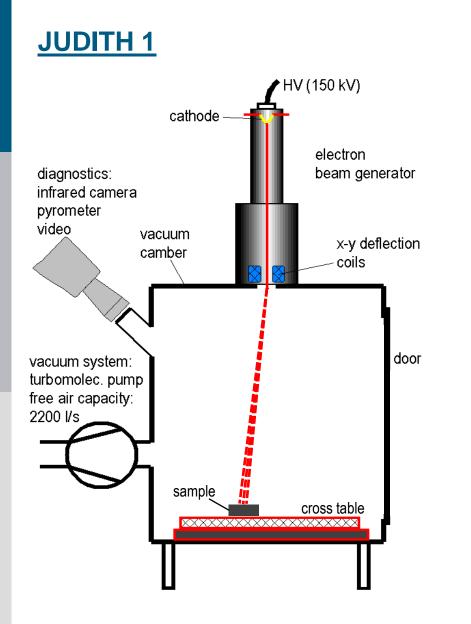
UFG & TFGR W-1.1TiC



By T. Sakamoto et al.

Facility, materials and loading conditions





Materials

<u>UFG</u>

• W-0.5TiC / H₂

<u>TFGR</u>

- W-1.1TiC / H₂, 1650 °C, ~800 ppm O
- W-1.1TiC / H₂, 1850 °C, ~800 ppm O
- W-1.1TiC / H₂, 1650 °C, ~200 ppm O

Loading conditions

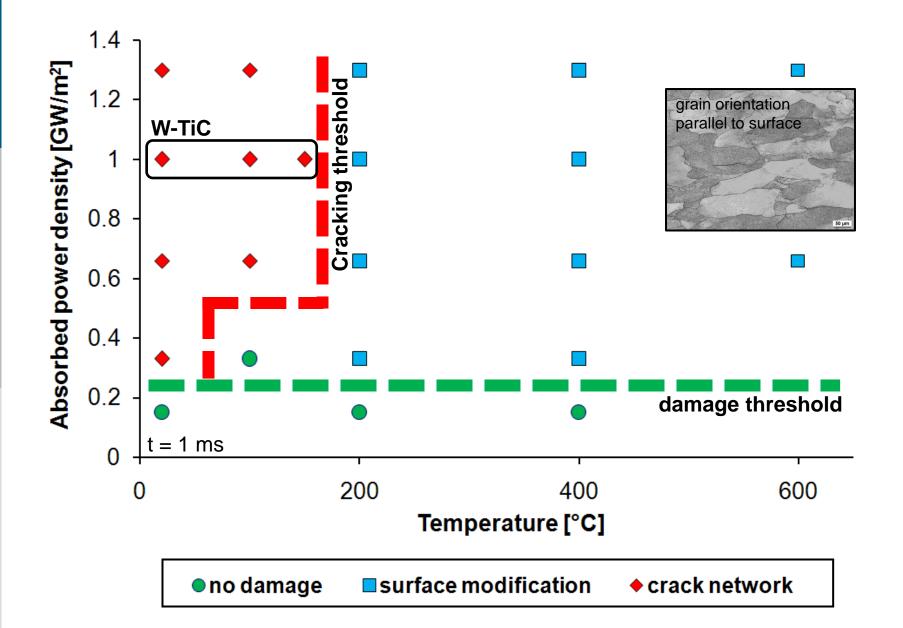
 $A = 16 \text{ mm}^2$

t = 1 ms

- P = 1.1 GW/m² (pure W: $\Delta T \approx 2000 \text{ °C}$)
- T_{base} = RT, 100 °C, 150 °C

n = 100

Thermal shock results: double forged tungsten

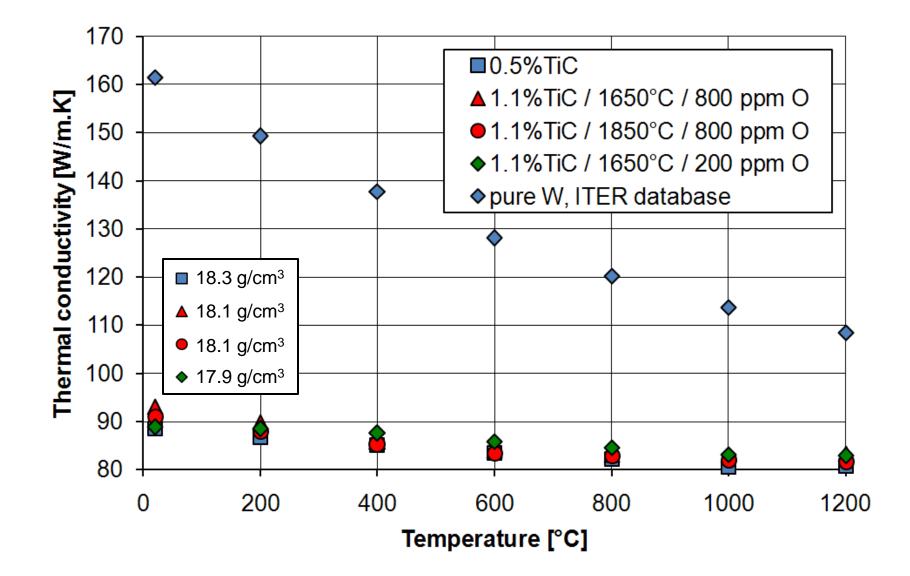


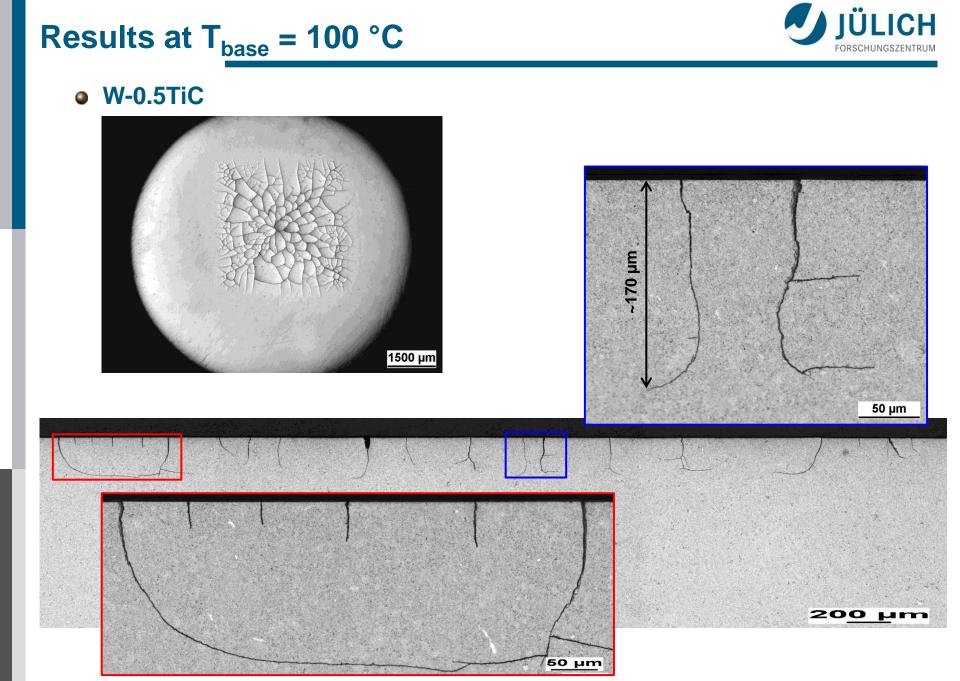
IÜLICH

FORSCHUNGSZEI

Thermal conductivity

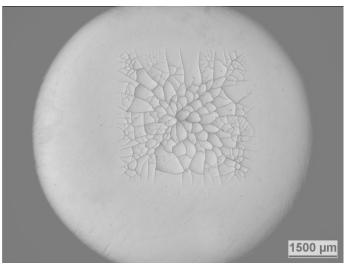




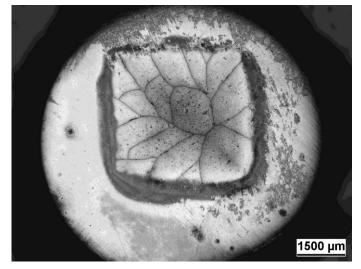


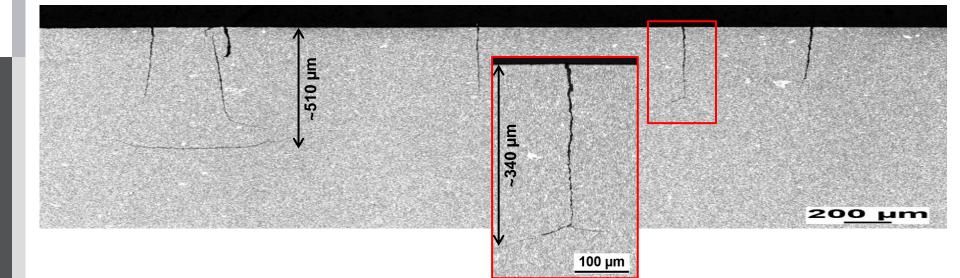


• W-0.5TiC



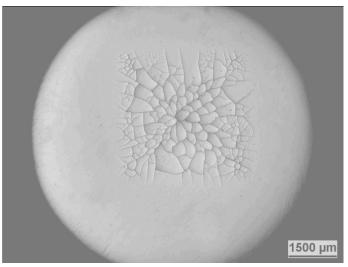
• W-1.1TiC / 1850°C / 800 ppm O



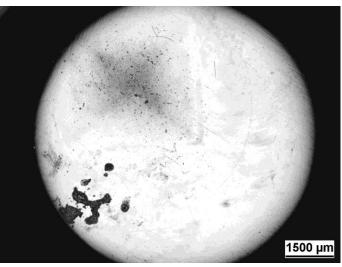




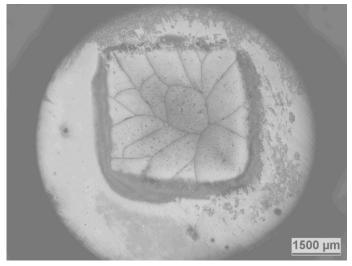
• W-0.5TiC



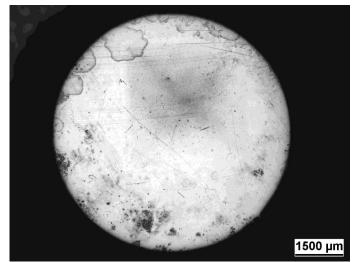
• W-1.1TiC / 1650°C / 800 ppm O



• W-1.1TiC / 1850°C / 800 ppm O

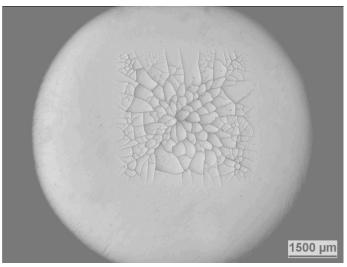


• W-1.1TiC / 1650°C / 200 ppm O

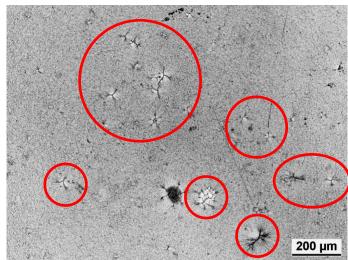




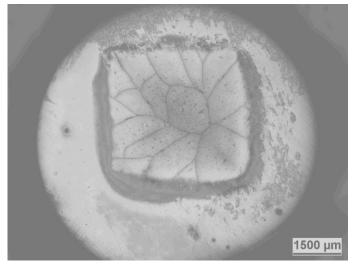
• W-0.5TiC



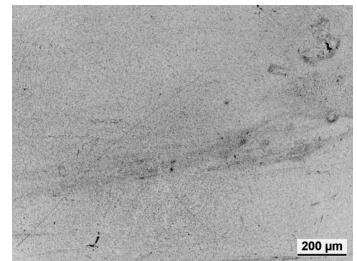
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• W-1.1TiC / 1850°C / 800 ppm O

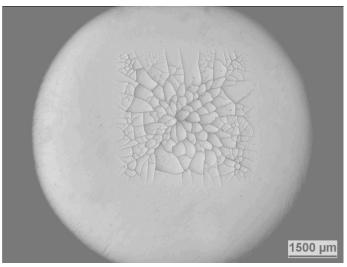


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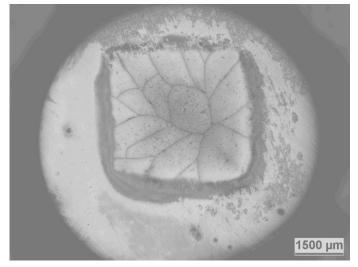




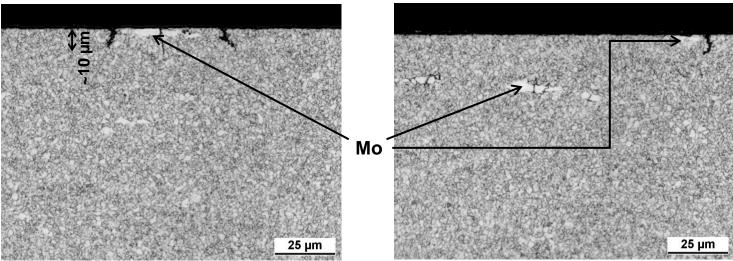
• W-0.5TiC



• W-1.1TiC / 1850°C / 800 ppm O



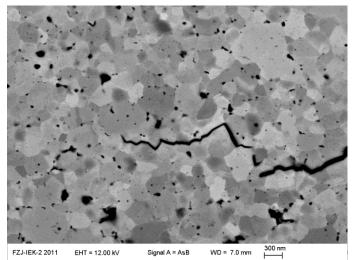
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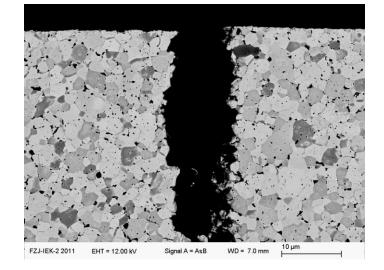
Microstructure & TiC-distribution



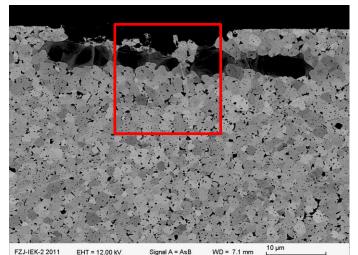
• W-0.5TiC

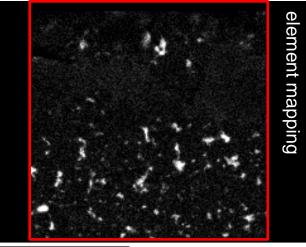


• W-1.1TiC / 1850°C / 800 ppm O



• W-1.1TiC / 1650°C / 800 ppm O \Rightarrow optimized grain size / TiC distribution

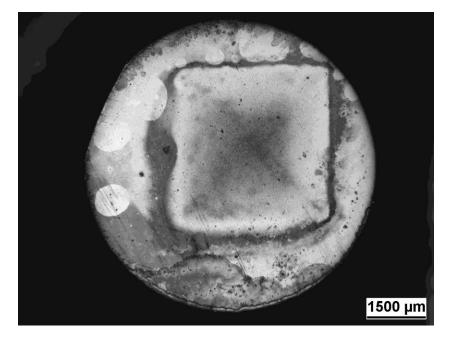




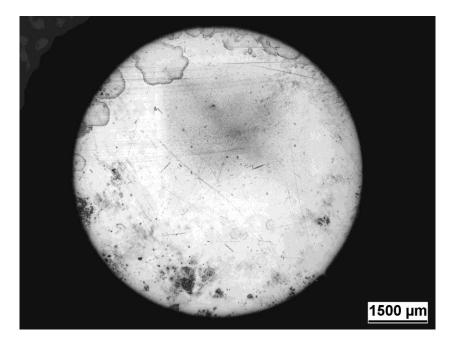
10µm Ti Ka1



• T_{base} = RT



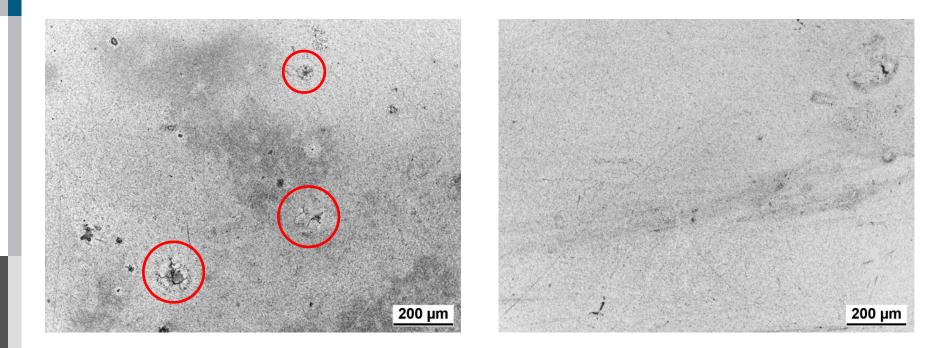












via laser profilometry no detectable surface roughening after 100 pulses

Conclusion



Improvement of

• cracking threshold $(T_{base} \downarrow \underline{to RT})$

of <u>W-TiC</u> due to

- TiC-content: 0.5 % \Rightarrow 1.1 % (UFG \Rightarrow TFGR)
- manufacturing temperature: $1850^{\circ}C \Rightarrow 1650^{\circ}C$
- oxygen content: 800 ppm \Rightarrow 200 ppm

Future work

- reduction of impurities (large Mo-grains) acting as crack initiation points
- investigation of thermal fatigue resistance as function of temperature
- H*, He*,**, neutrons** in combination with thermal shock / thermal fatigue
- industrial upscale???

* H. Kurishita et al., JNM 398, 2010, 87 ** H. Kurishita et al., JNM 377, 2008, 34